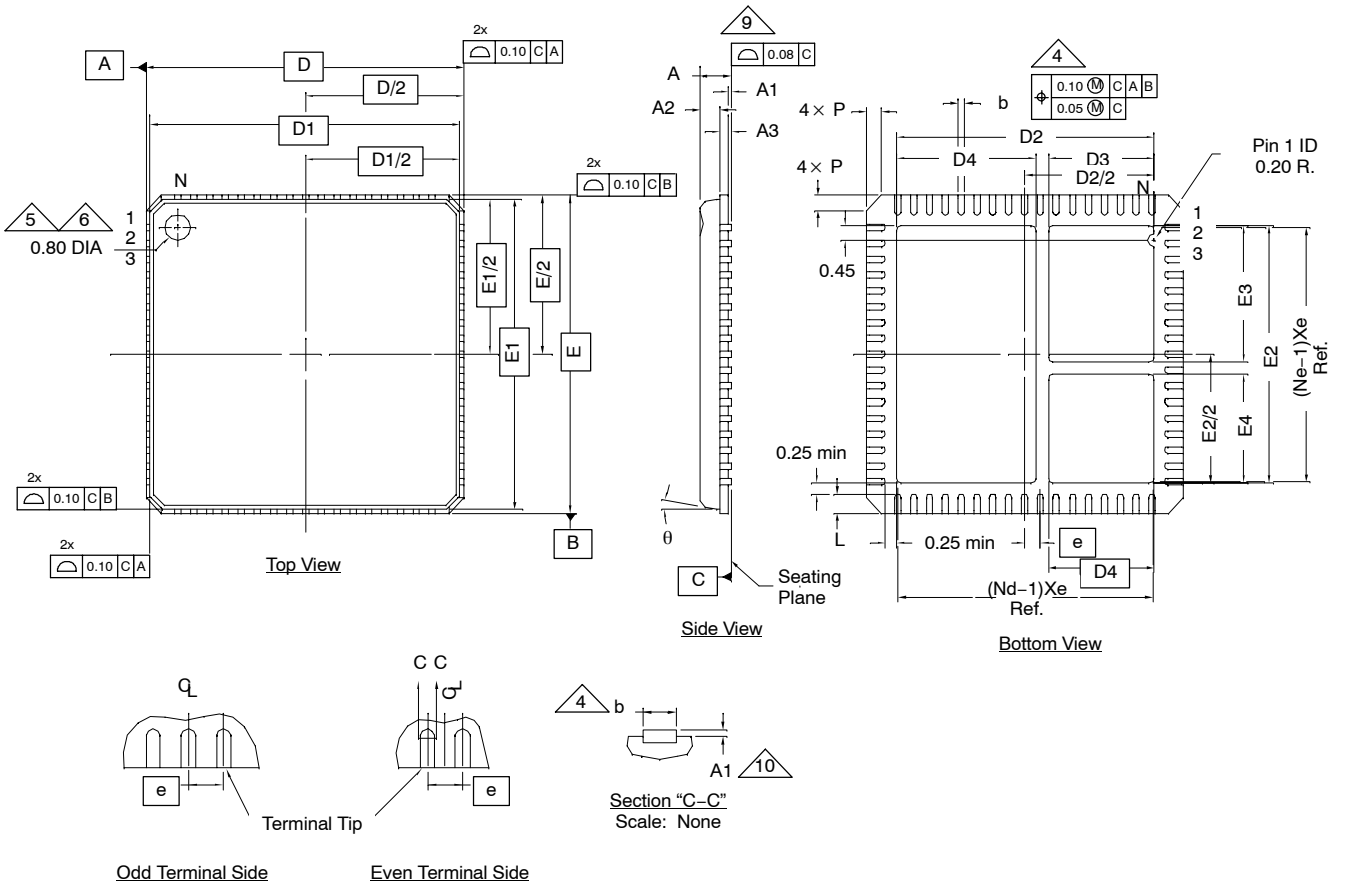
PowerPAK® MLF 10 × 10



EXPOSED PAD VARIATIONS (Millimeters)																				
D2			E2			D3			E3			D4			E4			D5		
Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
7.95	8.10	8.25	7.95	8.10	8.25	3.15	3.30	3.45	4.15	4.30	4.45	3.15	3.30	3.45	3.25	3.40	3.55	4.25	4.40	4.55
EXPOSED PAD VARIATIONS (Inches)																				
D2			E2			D3			E3			D4			E4			D5		
Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
0.313	0.319	0.325	0.313	0.319	0.325	0.124	0.130	0.136	0.163	0.169	0.175	0.124	0.130	0.136	0.128	0.134	0.140	0.167	0.173	0.179

NOTES:

1. Die thickness allowable is 0.305-maximum (0.12-inches maximum)
2. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
3. N is the total number of terminals. Pad from measuring, Nd is the number of terminals in the X-direction and Ne is the number of terminals in the Y-direction.
4. Dimension b applies to plated terminal and is measured between 0.20 mm and 0.25 mm from the terminal tip.
5. The pin #1 identifier must exist on the top surface of the package. The identifier may be an indentation mark or othe feature of the package body.
6. Exact shape and size of this feature is optional.
7. Millimeters will govern.
8. Package warpage maximum is 0.08 mm.
9. Applied for exposed pad and terminals exclude embedding part of exposed.
10. Applied only for terminals.

PowerPAK® MLF 10 × 10

DIMENSIONS							
	MILLIMETERS*			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	NOTE
A	—	0.85	0.90	—	0.033	0.035	
A1	0.00	0.01	0.05	0.000	—	0.002	10
A2	—	0.65	0.80	—	0.026	0.031	
A3		0.20 REF			0.008 REF		
b	0.18	0.23	0.30	0.007	0.009	0.012	4
D		10.00 BSC			0.394 BSC		
D1		9.75 BSC			0.384 BSC		
e		0.50 BSC			0.020 BSC		
E		10.00 BSC			0.394 BSC		
E1		9.75 BSC			0.384 BSC		
L	0.50	0.60	0.75	0.020	0.024	0.030	
N		68			68		3
Nd		17			17		3
Ne		17			17		3
P	0.24	0.42	0.60	0.009	0.017	0.024	
θ	—	—	12°	—	—	12°	

* Use millimeters as the primary measurement.

ECN: T-04698—Rev. A, 14-Feb-05
DWG: 5944